

Nome: dispositivo di vetro della scheda madre del telefono cellulare

Modello: BST-189

Materiale: vetro in lega di alluminio

Spessore di vetro: 3 mm

Dimensione del prodotto: 104*80*20mm

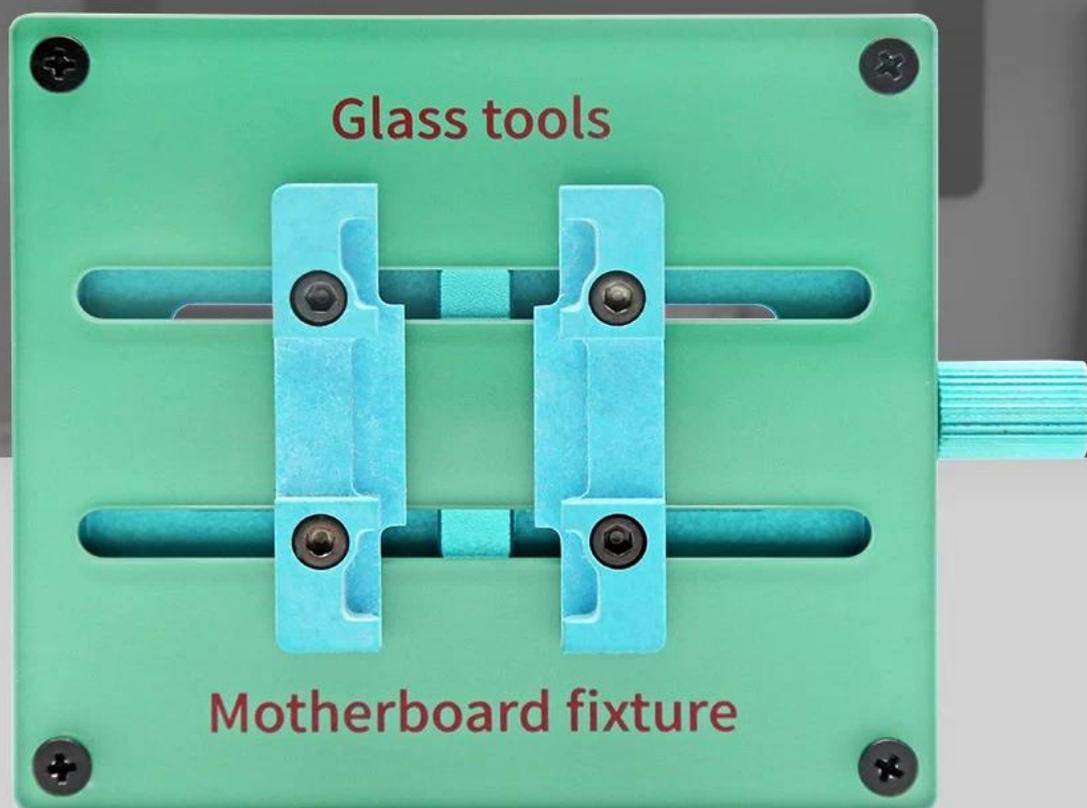
Dimensione del pacchetto: 112*84*23mm

N.W.: 224G

G.W.: 234G

MOBILE PHONE MOTHERBOARD HEAT INSULATING GLASS FIXTURE

Tempered glass / Corrosion resistance / High temperature resistance



Bidirectional bearings



Heat Insulating Glass



Corrosion resistance



Suitable for multiple motherboards

Specifications



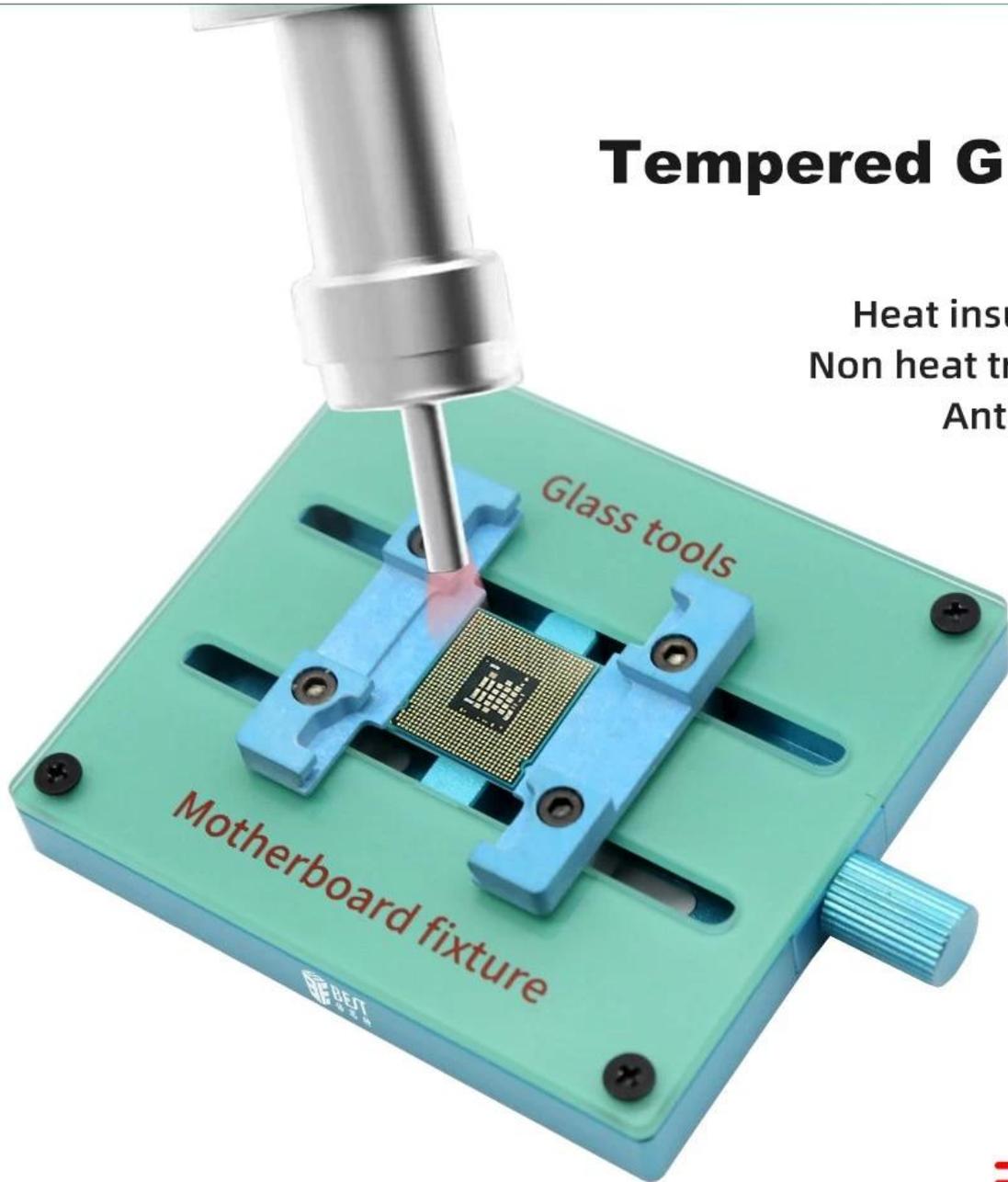
| | |
|-----------------|-------------------------------|
| Product Name | Motherboard Glass Fixture |
| Product Model | BST-189 |
| Material | Aluminum alloy+tempered glass |
| Glass Thickness | 3mm |
| Base Size | 90 * 80 mm |
| Product Size | 104 * 80 * 20mm |
| Package Size | 112 * 84 * 23mm |
| N. W. | 224g |
| G. W. | 234g |



Tempered Glass

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Heat insulation
Non heat transfer
Anti-static

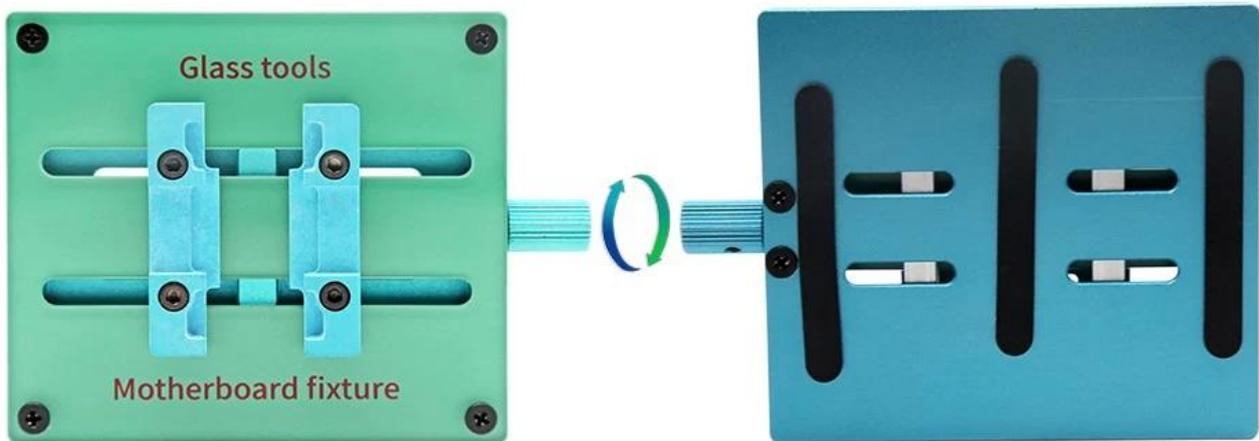


Concealed Screw Arbor



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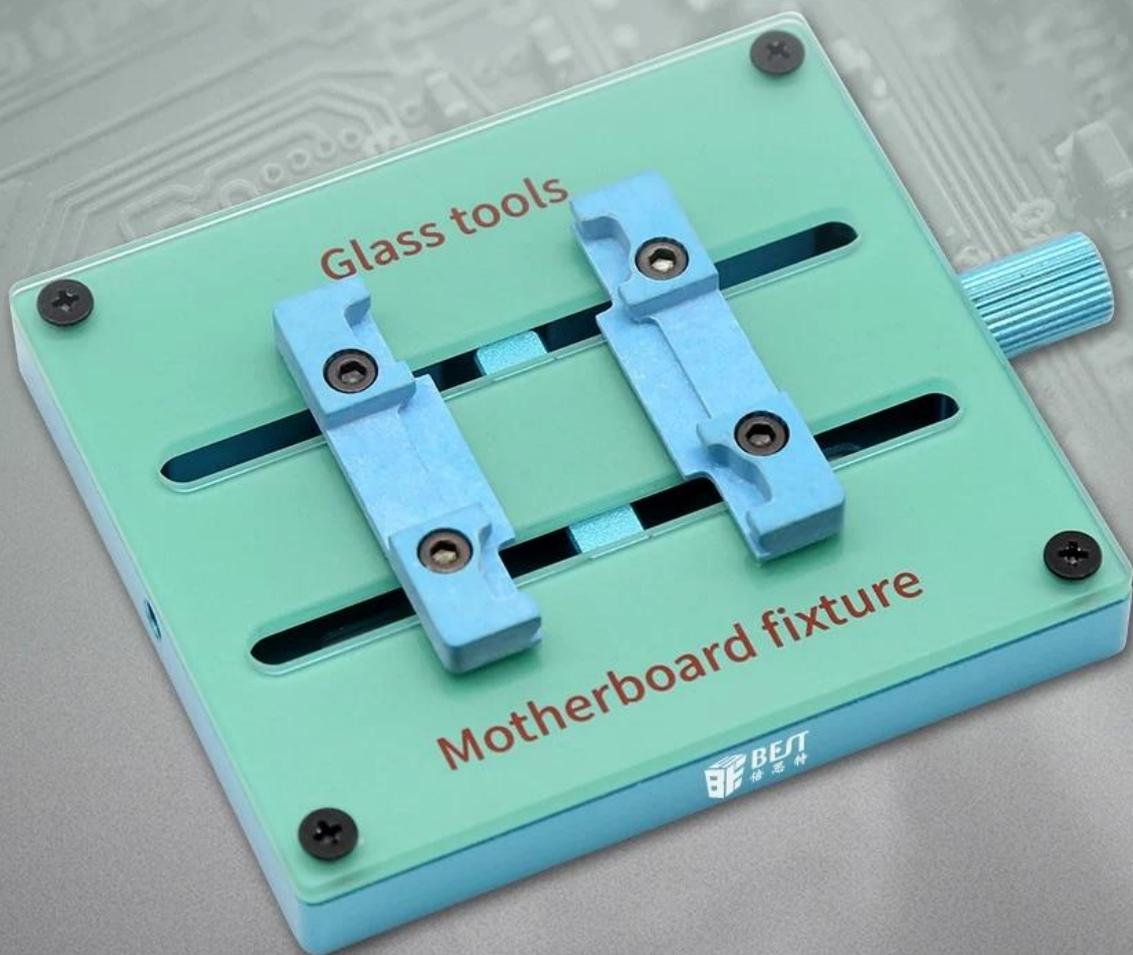
Flexible bidirectional adjustment
More durable and fastening



HEAT INSULATION GLASS

MOTHERBOARD GLASS FIXTURE

BST-189



Product Size

